Title (en)

A METHOD OF REPAIR OF SEMICONDUCTOR DEVICES

Title (de)

VERFAHREN ZUR REPARATUR VON HALBLEITERBAUELEMENTEN

Title (fr)

METHODE POUR REPARATION DES DISPOSITIFS A SEMI-CONDUCTEURS

Publication

EP 0953008 A1 19991103 (EN)

Application

EP 98904585 A 19980116

Priority

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- US 9800858 W 19980116

Abstract (en)

[origin: WO9831738A1] The present invention provides a thermosetting resin composition useful as an underfilling sealing resin which enables a semiconductor device, such as a CSP/BGA assembly which includes a semiconductor chip mounted on a carrier substrate, to be securely connected to a circuit boad by short-time heat curing and with good productivity, which demonstrates excellent heat shock properties (or thermal cycle properties), and permits the CSP/BGA assembly to be easily removed from the circuit board in the event of semiconductor device or connection failure.

IPC 1-7

C08K 5/09

IPC 8 full level

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